

Title (en)

METHOD FOR ELECTROPLATING OF CONTACT LAYERS ON CERAMIC COMPONENTS

Title (de)

VERFAHREN ZUM GALVANISCHEN AUFBRINGEN VON KONTAKTSCHICHTEN AUF KERAMISCHE BAUELEMENTE

Title (fr)

PROCEDE DE DEPOT PAR GALVANISATION DE COUCHES DE CONTACT SUR DES COMPOSANTS EN CERAMIQUE

Publication

**EP 1530654 A2 20050518 (DE)**

Application

**EP 02754511 A 20020808**

Priority

- DE 0202931 W 20020808
- DE 10147897 A 20010928

Abstract (en)

[origin: DE10147897C1] Process for directly galvanizing contact layers onto ceramic components comprises initially activating the regions (3) of the components (1) to be galvanized using chemical and mechanical treatment in an aqueous solution containing phosphoric acid and having a pH of 1.0-1.5; and applying the contact layers directly on the treated components using a galvanic process. Preferred Features: A high ohmic passivating layer is used in the first step, preferably a spinel of formula  $Ab_2O_4$  or perovskite of formula:  $MIIxMIII1-xTiIVx+yCoII11-y2yO_3$  (where MII = Sr or Ba; MIII = rare earth;  $x = 0-0.85$ ;  $y = 0-(1-x)/2$ ; and  $x+y$  is not more than 1), or a ceramic of the formula:  $(Pb, La)(Zr, Ti)O_3$ .

IPC 1-7

**C25D 5/54**

IPC 8 full level

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CPC (source: EP)

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